

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2635184

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIA HSIANG HSU</td> <td>11/11/2013</td> </tr> <tr> <td>HSIEN SEN CHIU</td> <td>11/11/2013</td> </tr> <tr> <td>SHIH PO SUN</td> <td>11/18/2013</td> </tr> <tr> <td>CHEN CHIEH WANG</td> <td>11/11/2013</td> </tr> <tr> <td>HUAN CHANG TSENG</td> <td>11/11/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHIA HSIANG HSU	11/11/2013	HSIEN SEN CHIU	11/11/2013	SHIH PO SUN	11/18/2013	CHEN CHIEH WANG	11/11/2013	HUAN CHANG TSENG	11/11/2013
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<table border="1"> <tr> <td>Name:</td> <td>CORETECH SYSTEM CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST.</td> </tr> <tr> <td>Internal Address:</td> <td>HSINCHU COUNTY</td> </tr> <tr> <td>City:</td> <td>CHUPEI CITY</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>30265</td> </tr> </table>		Name:	CORETECH SYSTEM CO., LTD.	Street Address:	TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST.	Internal Address:	HSINCHU COUNTY	City:	CHUPEI CITY	State/Country:	TAIWAN	Postal Code:	30265
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number:	(612)455-3801												
Phone:	6124553800												
Email:	adoyle@hsml.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	HAMRE, SCHUMANN, MUELLER & LARSON, P.C.												
Address Line 1:	P.O. BOX 2902												
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402												
ATTORNEY DOCKET NUMBER:	09751.1060USU1												
NAME OF SUBMITTER:	RONG YANG												

CH \$40.00 14091756

Signature:	/Rong Yang/
Date:	12/03/2013
Total Attachments: 3 source=Assignment_1060#page1.tif source=Assignment_1060#page2.tif source=Assignment_1060#page3.tif	

Docket No.

**ASSIGNMENT OF PATENT APPLICATION**

WHEREAS,

CHANG, Rong Yeu residing at TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST., CHUPEI CITY, HSINCHU COUNTY, 30265, TAIWAN, R.O.C. and a citizen of TAIWAN, R.O.C.

HSU, Chia Hsiang residing at TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST., CHUPEI CITY, HSINCHU COUNTY, 30265, TAIWAN, R.O.C. and a citizen of TAIWAN, R.O.C.

CHIU, Hsien Sen residing at TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST., CHUPEI CITY, HSINCHU COUNTY, 30265, TAIWAN, R.O.C. and a citizen of TAIWAN, R.O.C.

SUN, Shih Po residing at TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST., CHUPEI CITY, HSINCHU COUNTY, 30265, TAIWAN, R.O.C. and a citizen of TAIWAN, R.O.C.

WANG, Chen Chieh residing at TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST., CHUPEI CITY, HSINCHU COUNTY, 30265, TAIWAN, R.O.C. and a citizen of TAIWAN, R.O.C.

TSENG, Huan Chang residing at TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST., CHUPEI CITY, HSINCHU COUNTY, 30265, TAIWAN, R.O.C. and a citizen of TAIWAN, R.O.C.

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on , entitled

COMPUTER-IMPLEMENTED METHOD AND NON-TRANSITORY COMPUTER MEDIUM FOR CALCULATING SHRINKAGE OF MOLDING PRODUCTS , and which has been given application serial number ;

and

WHEREAS CORETECH SYSTEM CO., LTD. (hereinafter "ASSIGNEE") organized under the laws of TAIWAN, REPUBLIC OF CHINA and having an office and place of business at TAI YUEN HI-TECH INDUSTRIAL PARK 8F-2, NO.32, TAIYUAN ST., CHUPEI CITY, HSINCHU COUNTY, 30265, TAIWAN, R.O.C., wish to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEE, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the ASSIGNEE of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.


THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Chang, Rong Yeu      2013-11-11  
Signature - CHANG, Rong Yeu      Date

Hsu, Chia Hsiang      2013-11-11  
Signature - HSU, Chia Hsiang      Date

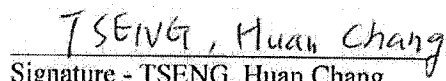
Chiu Hsien Sen      2013.11.11  
Signature - CHIU, Hsien Sen      Date

  
Signature - SUN, Shih Po

Nov. 18. 2013.  
Date

  
Signature - WANG, Chen Chieh

Nov. 11. 2013  
Date

  
Signature - TSENG, Huan Chang

Nov. 11, 2013  
Date